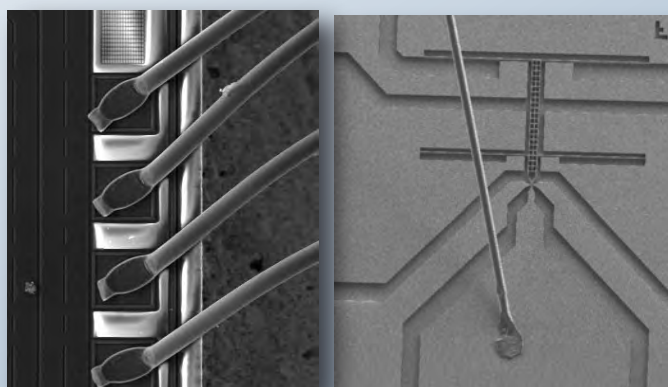
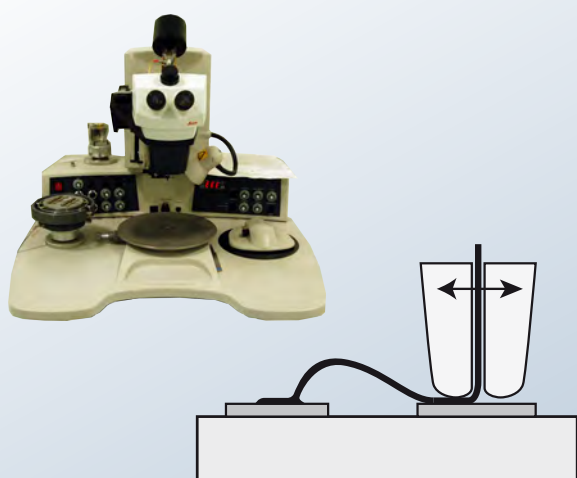
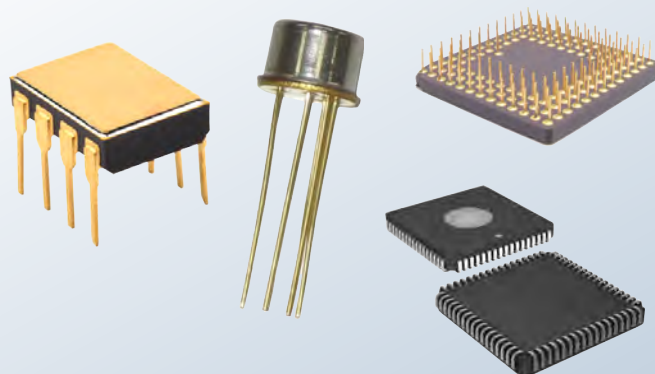


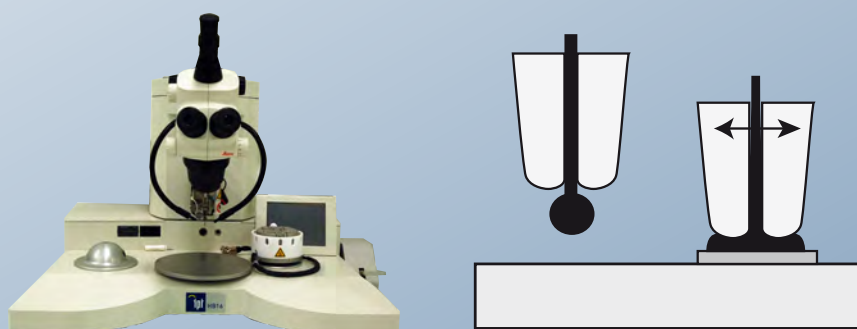
# Câblage et Microsoudure

Assemblage de puces sur boîtiers

→ Soudure par ultrasons  
*wedge bonding*



→ Soudure thermique  
*Ball bonding*



Centrale de Technologie  
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